

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: J. TAKETATSU, et al.
Serial No.: 10/585,461
371/Filing Date: MAY 27, 2009
For: CIRCUIT CONNECTION MATERIAL, FILM-SHAPED CIRCUIT
CONNECTION MATERIAL USING THE SAME, CIRCUIT
MEMBER CONNECTION STRUCTURE, AND
MANUFACTURING METHOD THEREOF
Group AU: 2835
Examiner: Hiram E. Gonzalez
Confirm. No.: 5965

AMENDMENT

Mail Stop: AMD - FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

January 19, 2012

Sir:

In response to the Office Action mailed August 19, 2011, the period for response having been extended for two (2) months by the attached Petition for Extension of Time, please amend the above-identified application as listed in the following, and as set forth on the following pages:

AMENDMENTS TO THE CLAIMS; and

REMARKS are included following the amendments.